

Heat Sink Paste | 25 g | Injection

General information

Heat sink compound suitable for PCBs in transistors, for diodes, CPUs etc.

Use it between -50 °C and 180 °C

25 g compound injection type.

Specifications

Packaging: Polybag

Content: 1 pc



Sales information

Order code: **HSPA25I**

Product description: Heat Sink Paste | 25 g | Injection

Packaging: Polybag

Brand name: Nedis



Quantity	LxWxH (mm)	Weight
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1	215x30x55	39 gr.
6	250x30x175	235 gr.
96	340x160x450	4200 gr.
192	360x350x485	9440 gr.